

sub. C1  
substrate, and having a cavity formed to store said electronic element therein; and  
a cover member to hermetically seal over the cavity of said frame member, in  
which said electronic element is stored, wherein electrodes are formed at or in  
vicinity of positions of the terminals of said electronic element stored within said  
cavity, to electrically conduct said interior terminal portions for connection to outside  
said electronic device, wherein said cover member, said frame member and said  
substrate form a hermetically sealed space in which said electronic element is stored  
without being in direct physical contact with any of the cover member, the frame  
member or the substrate.

22. An electronic device as defined in the claim 21, wherein said electrodes to  
electrically conduct said interior terminal portions to the outside are plated through-  
holes formed in said substrate, being filled with non-conductive resin therein.

23. An electronic device as defined in the claim 21, wherein said electrodes to  
electrically conduct said interior terminal portions to the outside are flat through-holes  
formed in said substrate.

24. An electronic device as defined in the claim 21, wherein exterior terminals for  
connection, being electrically connected with said internal terminal portion, are  
provided on a lower surface of said substrate.

25. An electronic device as defined in the claim 21, wherein conductors formed on  
said substrate, exposing to said cavity and the outside are made from layers of noble  
metal.